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TRANSMITTAL FORM <i>(to be used for all correspondence after initial filing)</i>	Application Number	09/321,715	
	Filing Date	May 28, 1999	
	First Named Inventor	Yasuhiko TAKEMURA et al.	
	Group Art Unit	2822	
	Examiner Name	M. Wilczewski	
Total Number of Pages in This Submission		Attorney Docket Number	740756-1974

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Docket No. 740756-1974

UNITED STATES PATENT AND TRADEMARK OFFICE

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In re PATENT Application of:)
Yasuhiko TAKEMURA et al.) Art Unit 2822
Application Serial No. 09/321,715) Examiner: M. Wilczewski
Filed: May 28, 1999)
For: SEMICONDUCTOR DEVICE AND PROCESS)
FOR FABRICATING THE SAME)

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the Office Action mailed **June 4, 2001**, please amend the above identified application as follows.

IN THE CLAIMS:

Please amend the claims as follows. Attached hereto is a marked-up version of the amended claims.

1. (Amended) A method of manufacturing a semiconductor device having a plurality of thin film transistors, comprising the steps of:
forming a semiconductor film comprising silicon over a glass substrate;
crystallizing said semiconductor film; and
oxidizing the crystallized semiconductor film to be active layers of said thin film transistors in a pressurized atmosphere at a temperature lower than a strain point of said glass substrate.